Supplier Name: Contact Info: Form/Declaration Type: Created on

# Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB

05/17/2022

# Details for "SN74LVC1GU04DBVR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
SN74LVC1GU04DBVR	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DBV   5	2.9x1.6x1.45	18.2

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information** 

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

# **Component Information**

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000002	0.009064	91	0.000011	0
Precious Metals	Gold	7440-57-5	0.022064	99.990936	999909	0.121335	1213
Sub-Total			0.022066	100	1000000	0.121346	1213
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.036286	72.999779	729998	0.199544	1995
Thermoplastics	Ероху	85954-11-6	0.013421	27.000221	270002	0.073805	738
Sub-Total			0.049707	100	1000000	0.273349	2733
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	5.651694	97.443	974430	31.079866	310799
Copper and Its Alloys	Iron	7439-89-6	0.1363	2.35	23500	0.749543	7495
Copper and Its Alloys	Phosphorus	7723-14-0	0.004756	0.082	820	0.026154	262
Zinc and Its Alloys	Zinc	7440-66-6	0.00725	0.125	1250	0.039869	399
Sub-Total			5.8	100	1000000	31.895432	318954
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.083706	95.120455	951205	0.460317	4603
Precious Metals	Gold	7440-57-5	0.000686	0.779545	7795	0.003772	38
Precious Metals	Palladium	7440-05-3	0.003608	4.1	41000	0.019841	198
Sub-Total			0.088	100	1000000	0.483931	4839
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	10.524914	86.995004	869950	57.878738	578787
Other Plastics and Rubber	Carbon Black	1333-86-4	0.060491	0.499996	5000	0.332653	3327
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.000605	0.005001	50	0.003327	33
Thermoplastics	Epoxy	85954-11-6	1.512287	12.499999	125000	8.316388	83164
Sub-Total			12.098297	100	1000000	66.531106	665311
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.126352	100	1000000	0.694836	6948
Sub-Total			0.126352	100	1000000	0.694836	6948
Total			18.184422			100	1000000

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

### Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one Ti part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different Ti part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

# Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

# Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

#### Important Information/Disclaimer

Th bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. The may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Thand Th suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by Th. The material content information is provided by Th "as

#### For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/17/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szaq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.